

Electronic Acknowledgement Receipt

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Title of Invention:	System and method for forming mold caps over integrated circuit devices
First Named Inventor:	Yoshimi Takahashi
Customer Number:	23494
Filer:	Yingsheng Tung/Jackie McBride
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Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		T37029_1_111.pdf	27101	yes	6

	Multipart Description		
	Doc Desc	Start	End
	Amendment - After Non-Final Rejection	1	1
	Claims	2	5
	Applicant Arguments/Remarks Made in an Amendment	6	6
Warnings:			
Information:			
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